

Fair-Rite P/N 2512065007Y6

Y Chip Bead Material Grade

Nominal Chemical Composition

<u>Ferrite -Compound</u>	<u>CAS Number</u>	<u>wt %</u>	Wt of core (g)=	
			0.024	
Fe2O3	1309-37-1	65	0.0156	Compound Weight (g) Breakdown of Y Chip Bead Material Grade
ZnO	1314-13-2	17	0.0041	
NiO	1313-99-1	9	0.0022	
CuO	1317-38-0	6	0.0014	
MnO	1344-43-0	3	0.0007	

<u>Termination Plating - Elements</u>	<u>CAS Number</u>	<u>wt %</u>	Wt of termination (g)=	
			0.006	
Sn	7440-31-5	14.3	0.00086	Element Weight (g) Breakdown of Pb- Free Termination Plating
Ni	7440-02-0	6.9	0.00041	
Ag	7440-22-4	78.8	0.00473	

Supporting notes:

1. P/N 2512065007Y6 consists of:
 - a core Y Chip Bead Material Grade
 - b Termination Plating SnNiAg
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 40 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
7. RoHS Compliance Marking is Contained on Shipping Labels

Calculated Maximum Levels of RoHS Restricted Substances Present in Y Material Grade

Impurity Substance	RoHS Threshold (ppm)	ppm	Substance Weight (g)
Hexavalent chromium (Cr+6)	1000	0.00	0
Cadmium (Cd)	100	0.00	0
Mercury (Hg)	1000	0.00	0
Lead (Pb)	1000	0.00	0
Polybrominated biphenyl (PBB)	1000	0.00	0
Polybrominated diphenyl (PBDE)	1000	0.00	0
Bis(2-Ethylhexyl) phthalate (DEHP)	1000	0.00	0
Benzyl butyl phthalate (BBP)	1000	0.00	0
Dibutyl phthalate (DBP)	1000	0.00	0
Diisobutyl phthalate (DIBP)	1000	0.00	0